ASSEMBLY NOTES:
ASSEMBLIES MUST BE CLEAN AND FREE FROM FLUX AND ALL CONTAMINANTS. USE OF NO CLEAN FLUX IS NOT ACCEPTABLE
ASSEMBLIES MUST COMPLY WITH WORKMANSHIP STANDARDS IPC-A-610 CLASS 2, UNLESS OTHERWISE SPECIFIED
COMPONENTS MARKED "DNI = TRUE" WILL NOT BE ASSEMBLED

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IWR1443BOOST
PROC010

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1) Power and 2 GPIO LED indicators.
2) RST and GPIO manual switch.

- 5V i/p from jack/ MCU
- Current measurement
- EN control from the MCU
- PGOOD signal to MCU for power sequencing
- Option for 3.3V from the MCU launched

- UART & JTAG
- 4 RX and 3 TX PCB antennas
- SPI, UART, I2C, RTs, Nems, SOPs, Loggers, CAN, GPIOs
- Control signals for TDA3 interface

5678 5678
CONTROLS FOR THE PMIC

THE 3V3 OUTPUT FROM PMIC IS USED AS PGOOD.

THE 3V3 OUTPUT FROM PMIC IS USED AS PGOOD.

PMIC (3.3V, 1.2V, 1.8V, 2.3V OUTPUTS)
GETS ENABLED ONLY ONCE THE PMIC IS POWERED UP.

BY DEFAULT THE XDS SUPPLY IS DISABLED...

GETS ENABLED ONLY ONCE THE PMIC IS POWERED UP.
CAN INTERFACE

- R86 10K R87 61.9
- R85 61.9
- C16 0.1UF
- C20 0.1UF
- J3
- AR_MISO1
- AR_MOSI1
- SN65HVDAS40
- CAN INTERFACE

Drawing No.

Texas Instruments

Semiconductor Operations

09/5/2016

Code Identity Number

01295

Size

Drawing No.

IWR144JBOOST

Rev.

A

Can Interface

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ONBOARD TEMP SENSORS

TEMP SENSOR CLOSE TO PMIC

DEFAULT I2C ADDRESS : 0X48

TEMP SENSOR AWAY FROM PMIC AND MMwave DEVICE

DEFAULT I2C ADDRESS : 0X49
REVISION HISTORY

CHANGES IN REV A

1) ADDED ZENER DIODE ON 5V INPUT TO PROTECT FROM HIGH VOLTAGES.
2) ADDED ONBOARD TEMPERATURE SENSORS.
3) ADDED FERRITE BEAD ON 5V SUPPLY.
4) CHANGED THE PMIC PART TO PG2.2 VERSION
5) ADDED DUMMY ANTENNAS FOR RX
6) ADDED PM DEBUG PROVISION FOR LDO BYPASS
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PCB LABELS: THESE LABELS NEED TO BE PUT ON THE ASSEMBLED PCB
1) TOP SIDE OF THE PCB -> IWR1443BOOST
   REV A
2) BOTTOM SIDE OF THE PCB -> IWR1443BOOST
   REV A

COMPONENTS MARKED "DNI = TRUE" WILL NOT BE ASSEMBLED
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